

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
3 October 2002 (03.10.2002)

PCT

(10) International Publication Number
WO 02/076753 A1

(51) International Patent Classification⁷: **B41J 2/235**

(21) International Application Number: PCT/AU02/00374

(22) International Filing Date: 27 March 2002 (27.03.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
PR 3996 27 March 2001 (27.03.2001) AU

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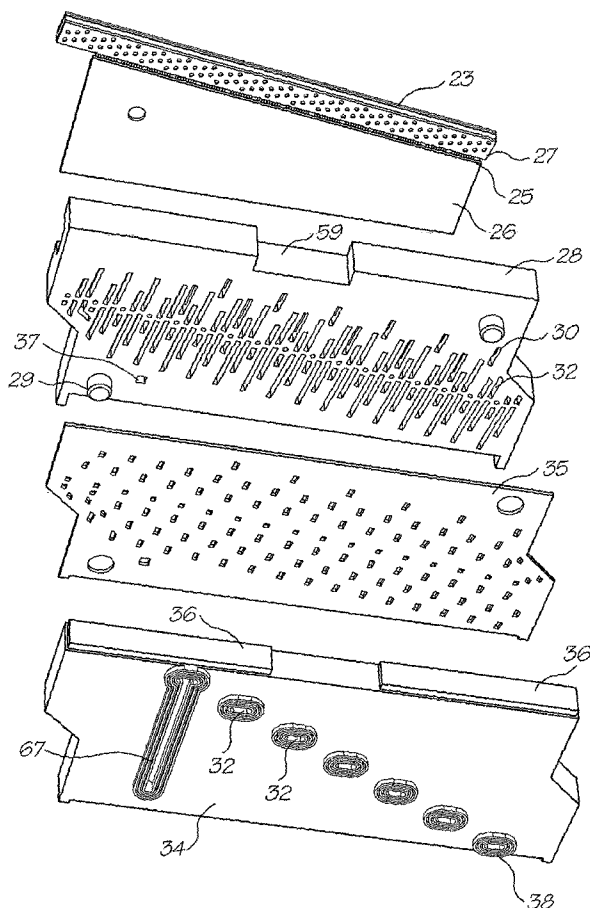
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(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZM, ZW.

(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),

[Continued on next page]

(54) Title: PRINTHEAD MODULE ASSEMBLY



(57) Abstract: A printhead module (11) for a printhead assembly (10) incorporating a number of modules spaced across a pagewidth in a drop on demand ink jet printer includes an upper micro-molding (28) and a lower micro-molding (34) separated by a mid-package film layer (35). The mid-package film layer has laser ablated holes (65) and an adhesive layer on both faces providing adhesion between the upper micro-molding, the mid-package film layer and the lower micro-molding. The upper and lower micro-moldings are held in alignment by pins (29) passing through corresponding apertures in the mid-package film layer. Ink inlets (32) and an air inlet (67) are provided in the underside of the lower micro-molding. Ink and air passes from the lower micro-molding, through the mid-package film layer to the upper micro-molding. Air exits the upper micro-molding to repel the print media from the printhead during printing. The ink passes from the upper micro-molding into individual print chips mounted therein.



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Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR,
GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent
(BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR,
NE, SN, TD, TG).

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